Special Track on Wearable-technology Enhanced Learning (WELL) at the Immersive Learning Research Network Conference iLRN 2017
June 26-29, 2017, Coimbra, Portugal
https://immersivelrn.org/ilrn2017/

Topic of the Special Track

Wearable technologies – such as smart watches, smart glasses, smart objects, smart earbuds, or smart garments – are just starting to transform immersive user experience into formal education and learning at the workplace. These devices are body-worn, equipped with sensors and conveniently integrate into leisure and work-related activities including physical movements of their users. Wearable-technology Enhanced Learning (WELL) is beginning to emerge as a new discipline in technology enhanced learning in combination with other relevant trends like the transformation of classrooms, new mobility concepts, and cyber-physical systems. Wearable devices play an integral role in the digital transformation of industrial and logistics processes in the Industry 4.0 and thus demand new learning and training concepts like experience capturing, re-enactment and smart human-computer interaction.

This proposal of a special track is the offspring of the SIG WELL (http://eateleu/special-interest-groups/well/) in the context of the European Association for Technology Enhanced Learning (EATEL). It is a follow up proposal for the inaugural session we had at the iLrn 2015 in Prague. In the meantime, the SIG was successful in organizing a number of similar events at major research conferences and business oriented fairs like the EC-TEL, the I-KNOW and the Online Educa Berlin OEB. Moreover, the SIG has involved in securing substantial research funds through the H2020 project WEKIT (www.wekit.eu). The SIG would like to use the opportunity to present itself as a platform for scientific and industrial knowledge exchange. EATEL and major EU research projects and networks in the field support it. Moreover, we’ll seek to attach an IEEE standard association community meeting of the working group on Augmented Reality Learning Experience Models (IEEE ARLEM).

List of Topics

- Industry 4.0 and wearable enhanced learning
- Learning Analytics for Wearable technologies
- Wearable technologies for health and fitness
- Wearable technologies and affective computing
- TEL applications of smart glasses, watches, armbands
- Learning context and activity recognition for wearable enhanced learning
- Body-area learning networks with wearable technologies
- Data collection from wearables
- Feedback from wearables
- Learning designs with wearable technologies
- Augmented Reality Learning
- Ad hoc learning with wearables
Micro learning with wearables
Security and privacy for wearable technology enhanced learning
Collaborative wearable technology enhanced learning

Dates

Paper submission: February 1, 2017
Notification of authors: March 15, 2017
Full paper submission: April 15, 2017
Date of the conference: June 26-29, 2017

Contributing papers have to undergo a peer review process and will be included in the conference proceedings, depending on the overall quality and special tracks chairs’ decision, either as a long paper (10 – 12 pages) or as a short paper (6 - 8 pages). Excellent papers will be deemed full papers (14 pages) and included in the Springer proceedings. Authors of selected papers will also be invited to extend their contribution and to be published in a special issue of the JCR-indexed Journal of Universal Computer Science.

Track chairs

Ilona Buchem, Beuth University of Applied Sciences Berlin, Germany
Ralf Klamma, RWTH Aachen University, Germany,
István Koren, RWTH Aachen University, Germany
Fridolin Wild, Oxford Brookes University, UK
Alla Vovk, Oxford Brookes University, UK

Tentative Program Committee (t.b.c.)

Mario Aehnelt, Fraunhofer IGD Rostock, Germany
Davinia Hernández-Leo, Universitat Pompeu Fabra, Spain
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Yishay Mor, Levinsky College of Education, Israel
Tobias Ley, Tallinn University, Estonia

Peter Scott, Sydney University of Technology, Australia